



PLASMA DECAP SYSTEM

PLT PD2



PLT

Device Failure Analysis

Semiconductor chips are widely used in various high-end electronic devices from smartphones to artificial intelligence servers, and can be regarded as the cornerstone of the information age. However, in complex manufacturing processes and long-term use, semiconductors are prone to failure problems, which undoubtedly poses a huge challenge to the entire supply chain of the electronics industry. At this point, semiconductor failure analysis becomes a crucial part, like a precise surgical knife, deeply analyzing the root cause of problems, ensuring product quality, and promoting technological iteration. The plasma decap system plays an indispensable role in this critical field, focusing on the tiny structural units of semiconductors with its unique technological advantages, helping engineers penetrate the fog of failure, uncover the truth hidden at the microscopic level, and reshape the infinite possibilities of chips.

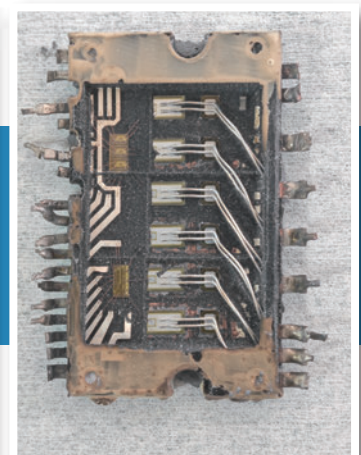
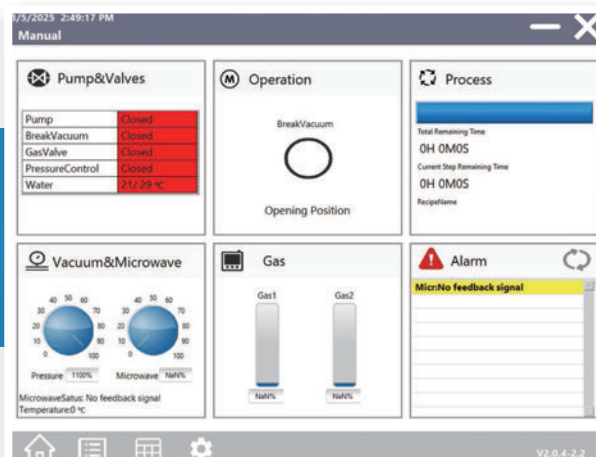
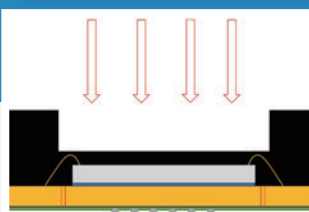
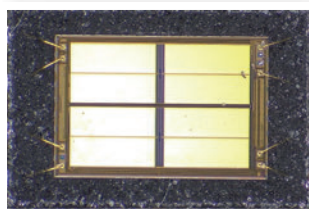
Plasma decap advantage

Unlike traditional RIE reaction ion etching equipment, the PLT plasma decap machine uses microwave as the plasma source, which has a higher frequency (2.4GHz) and power (up to 1000W), making it more suitable for decap electronic components. The PLT plasma decap machine uses vacuum plasma technology to input reaction gas into a vacuum chamber to form plasma, consuming less reaction gas. Simultaneously using a gas generator, the generation of gas is controlled by a program, no need for gas tank, and no safety issue need to be taken in terms of gas storage and use.

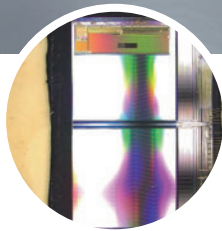
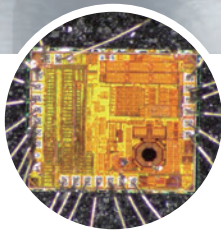
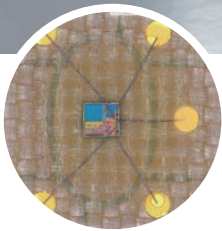
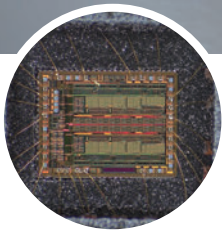
PLT decap system

Unlike traditional RIE reaction ion etching equipment, the PLT plasma decap machine uses microwave as the plasma source, which has a higher frequency (2.4GHz) and power (up to 1000W), making it more suitable for electronic device decap. The PLT plasma decap system uses vacuum plasma technology to input reaction gas into a vacuum chamber to form plasma, consuming less reaction gas. Simultaneously using a gas generator, the generation of gas is controlled by a program, no need for gas tank, and no safety issue need to be taken in terms of gas storage and use.

The vacuum plasma of the PLT plasma decap system can cover a large area and react with samples with a diameter range of 70mm. Therefore, it can simultaneously decap multiple different samples, effectively improving the efficiency of decap. In addition, for testing and other requirements after decap, a special adhesive can be used to protect the areas that need to be preserved, and they can be removed after decap.



NOT ONLY DECAP



Feature

- Just O2 and H2, no die damage
- Use gas generator only
- Decap multiple samples one time
- No extra facility requirement
- Easy to operate

Specification

- Microwave power: 1000W
- Reaction gas: O2, H2
- Power: 220V, 2500W, 1 phase
- Stage size: 70mm diameter
- Size : 128x84x170cm



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